

ABSTRACT OF THE DISCLOSURE

A positive photoresist composition comprising:

(A) an oxime sulfonate compound represented by the specific formula,

(B) a resin comprising repeating units including a group represented by the specific formula and which increases the solubility in an alkaline developing solution by the action of an acid, and

(C) a fluoroaliphatic-group-containing polymeric compound containing repeating units derived from a monomer represented by the specific formula.